

# DA108S1 DA112S1

## Main applications

- Protection of logic side of ISDN S-interface
- Protection of I/O lines of microcontroller
- Signal conditioning

### Features

- Array of 8 or 12 diodes
- Low input capacitance
- Suitable for digital line protection

## Description

ARRAY of 8 or 12 diodes configured by cells of 2 diodes, each cell being used to protect signal line from transient overvoltages by clamping action.

# COMPLIES WITH FOLLOWING STANDARDS :

IEC 61000-4-2 Level 4:

- 15kV (air discharge)
- 8kV (contact discharge)



## Functional diagram: DA108S1



## Functional diagram: DA112S1



Diode Array

# 1 Characteristics

## Table 1. Absolute maximum ratings (T<sub>amb</sub> = 25 °C)

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage (for one single diode)	200	V	
I <sub>PP</sub>	Repetitive peak forward current (see <i>Note 1</i> ) 8/20 µs		100	А
Р	Power dissipation	0.73	W	
T <sub>stg</sub>	Storage temperature range	-55 to + 150	°C	
Тj	Maximum operating junction temperature	150	°C	
TL	Maximum lead temperature for soldering during 10 s.	260	°C	

## Note: 1 The surge is repeated after the device returns to ambient temperature

# Table 2.Thermal resistancesSymbolParameterValueUnitR<sub>th (j-a)</sub>Junction to ambient170°C/W

## Table 3. Electrical characteristics(T<sub>amb</sub> = 25 °C)

Symbol	Parameter			Max.	Unit
I <sub>R</sub>	Peak forward voltage	I <sub>PP</sub> = 12 A, 8/20 μS	DA108S1	9	v
			DA112S1	12	
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 50 mA		1.2	V
I <sub>R</sub>	Reverse leakage current	V <sub>R</sub> = 15 V		2	μA

Figure 1. Input capacitance









57



# Figure 3. APPLICATION 1: ISDN Interface ProtectionResidual lightning surges at transformer secondary are suppressed by DA108S1

## Figure 4. APPLICATION 2: Microcontroller I/O port protection



Note:

**IMPORTANT** : DA108S1 must imperatively be connected to the reference voltages by REF1 and REF2.

# 2 Ordering information scheme

	DA 1 08 S 1 RL
Diode Array	
Version	
Number of diodes	
08 = 12	
12 = 12	
Serial	
Package	
1 = SO-8	
Packaging	
RL = Tape & reel	
Blank = Tube	



# 3 Package mechanical data

• Epoxy meets UL94, V0

### Table 4.SO-8 Dimensions



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

57

# 4 Ordering information

Part number	Marking	Package	Weight	Base qty	Delivery mode
DA108S1	DA108S	SO-8	0.11 g	100	Tube
DA108S1RL	DATU65			2500	Tape and reel <sup>(1)</sup>
DA112S1	DA112S			100	Tube
DA112S1RL	DATIZO			2500	Tape and reel <sup>(1)</sup>

1. Preference packaging is tape and reel

# 5 Revision history

Date	Revision	Changes
Aug-2001	4	Last release.
15-Feb-2007 5		Reformatted to current standard. Standard typing error corrected.



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